



承認書

SPECIFICATION FOR APPROVAL

CUSTOMER:

DESCRIPTION:

WIRE WOUND CHIP INDUCTOR

PART NO:

MWI1812PS系列

CUST. PART NO:

REV. NO.

A0

DRAWING		
PREPARED	CHECKED	APPROVED
邹声平	卢嘉良	曾凡强
DATE:	2025/5/1	

CUSTOMER APPROVE



东莞市铭易轩电子科技有限公司

DongGuan Ming Yixuan Electronic Technology Co., LTD

地址: 广东省东莞市大朗镇景泰路20号VV大厦

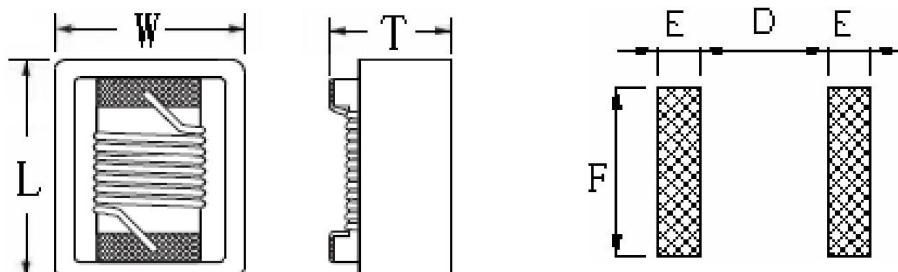
电话: 15970768093 , 13640935893

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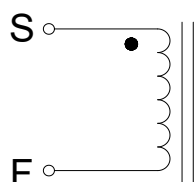
1. SHAPE & DIMENSION (UNIT:mm)



Recommended patterns

L	W	T	E	F	D
5.87 Max.	4.98 Max.	4.20 Max.	1.14 Typ.	3.05 Typ.	3.00 Typ.

2. SCHEMATIC



3. PART NUMBERING SYSTEM

MWI	1812	PS	4R7	M	S	T	-	HF
1	2	3	4	5	6	7		8

1 PRODUCT SYMBOL (产品代号)

2 DIMENSIONS (规格尺寸)

3 MATERIAL (芯片类型)

4 INDUCTANCE (电感量)

5 TOLERANCE (公差) M±20%

6 TERMINAL (端电极材料): S-锡端头;

7 PACKAGING (包装方式): T-编带盘装; B-散装

8 E.P. (环保): LF—Lead Free HF—Halogen Free FP—Red Phosphor Free

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4. ELECTRICAL CHARACTERISTICS

No.	Part Number	L	Freq	Q	SRF	Rdc	Idc 15%
		(μ H)	(MHz)	Min.	(MHz)Min.	(Ω) Max.	(A)Max.
1	MWI1812PS2R2MST-HF	2.2	100/0.1	35	170	0.10	1.70
2	MWI1812PS3R3MST-HF	3.3	100/0.1	35	150	0.09	1.40
3	MWI1812PS4R7MST-HF	4.7	100/0.1	35	140	0.11	1.15
4	MWI1812PS100MST-HF	10	100/0.1	35	70	0.17	0.71
5	MWI1812PS220MST-HF	22	100/0.1	30	45	0.33	0.54
6	MWI1812PS470MST-H	47	100/0.1	20	28	0.87	0.35
7	MWI1812PS331MST-HF	330	100/0.1	18	5.5	5.50	0.15
8	MWI1812PS471MST-HF	470	100/0.1	16	4.0	6.90	0.12
9	MWI1812PS561MST-HF	560	100/0.1	16	2.6	8.40	0.11

产品公差: M $\pm$ 20%**Test remarks**

(1). All test data is referenced to 25 °C ambient.

5. GENERAL SPECIFICATION

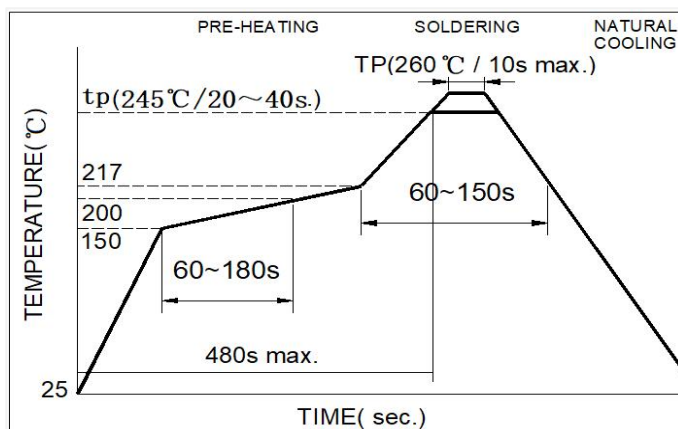
- (1). Operating temp.: -40°C ~ +85°C (Including self-generated heat).
- (2). Storage temp.: -10°C ~ +40°C R.H.:60% Max.
- (3). Moisture sensitivity level (MSL) 1
- (4). Recommended products should be used within 12 months from the date of delivery
- (5). The part temperature (ambient + temp rise) should not exceed 85 °C under worst case operating conditions. Circuit design, component placement, PWB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.

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6. SOLDERING CONDITIONS

Figure 1. Re-flow Soldering (Lead Free)



Note:

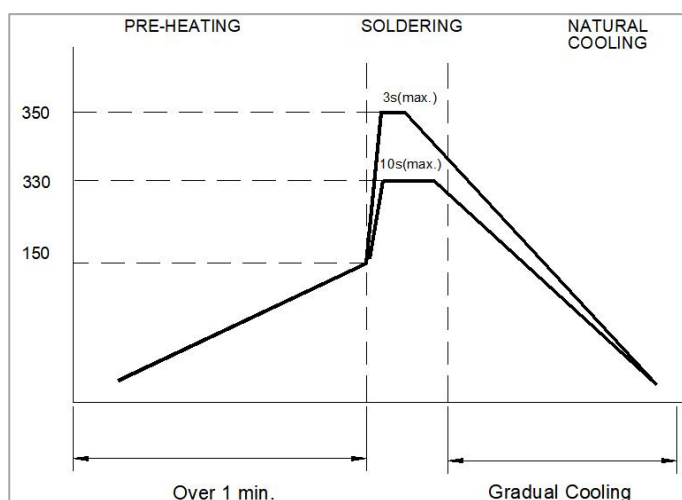
Preheat circuit and products to 150°C

260°C tip temperature (Max)

Reflow times: no more than 2 times

Solder paste thickness: the best 0.08mm is ,but max is 0.1mm

Figure 2. Hand Soldering



Note:

Use a 20 watt soldering iron with tip diameter of 1.0mm

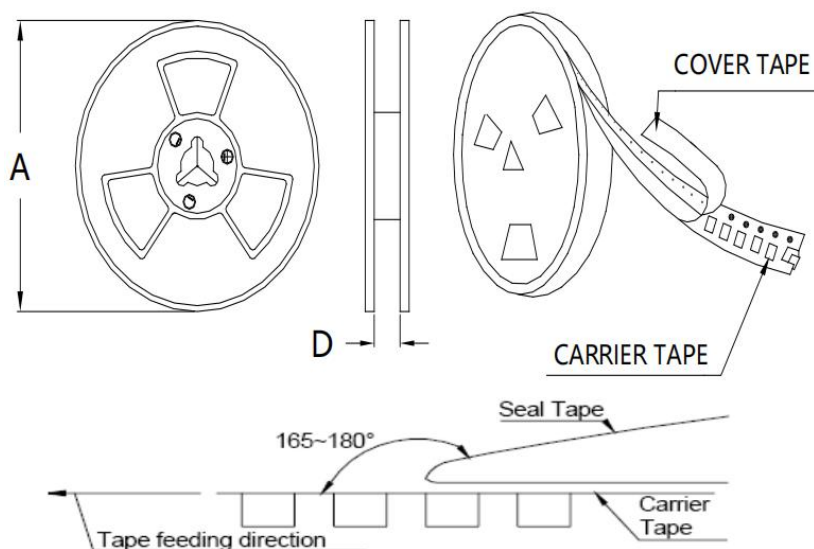
Limit soldering time to 3 sec.

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7. PACKAGE SPECIFICATION

1.包装类型: 编带装

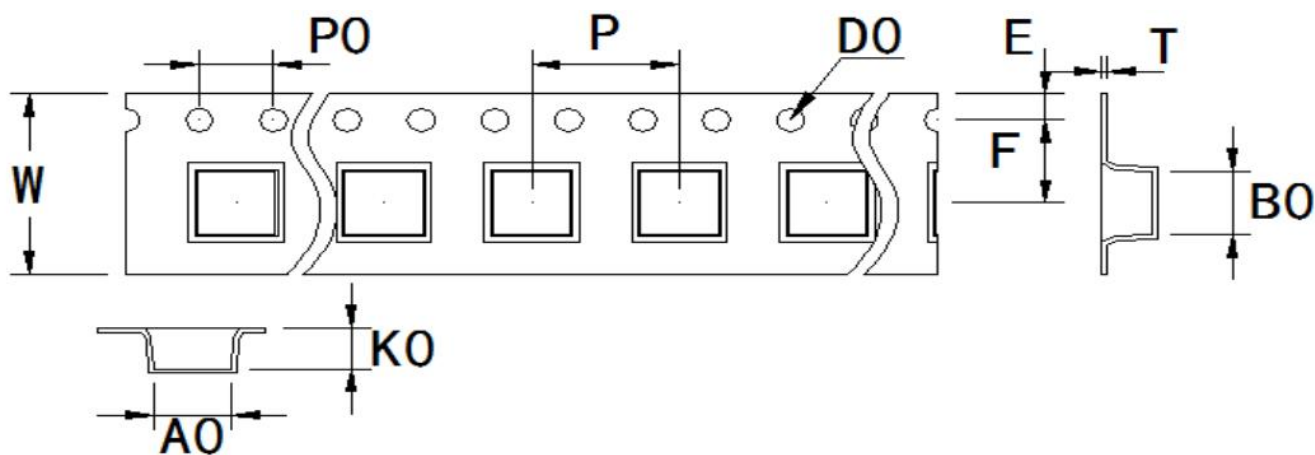
 2.包装尺寸: ☒ 13" 盘 ☐ 7" 盘


	13" 盘	7" 盘
A	$\Phi 330 \pm 2.0$	$\Phi 178 \pm 2.0$
D	12.5	

Peel-off strength: 10~100gf.

Peel-off angle: 165°-180°

Peel-off speed: 300mm/min.



Item	W	A0	B0	K0	P	T	E	F	D0	P0
DIM(mm)	12.0±0.3	5.2±0.15	6.0±0.1	4.0±0.1	8.0±0.1	0.35±0.1	1.75±0.1	5.5±0.1	1.5±0.1	4.0±0.1

包装数量: 1500PCS / 卷

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